

TECHNICAL DATA SHEET Semiconductor Solutions

STAYSTIK® 892

Alumina Filled "Low Flow" Dielectric Film

DESCRIPTION

These thermoplastic adhesive films are designed for use in a variety of electronic applications. These materials are characterized by their excellent bonding at low process temperatures. The properties of this adhesive family make it exceptional for heat sink bonding to BGA as well as TAB bonding to PCB. The unique reworkability of this thermoplastic adhesive system offers many advantages in applications traditionally ill-suited to thermoset adhesives.

READ ENTIRE TECHNICAL DATA SHEET BEFORE USING THIS PRODUCT

KEY FEATURES AND BENEFITS

- Fully Polymerized resin No "Cure"
- Easily Reworkable No Outgassing
- Bonds in Seconds Not Hours or Minutes
- Low Modulus Reduces Stress to Bonded Material

TYPICAL PROPERTIES

Typical Properties	591	692	492	892
Filler Material	Silver	AIN	None	Alumina
Attach Temperature Range	150 to 220 °C	150 to 220 °C	150 to 220 °C	150 to 220 °C
Continuous Use Range	-65 to 150 °C	-65 to 150 °C	-65 to 150 °C	-65 to 150 °C
Max Excursion Temperature	280 °C	280 °C	280 °C	280 °C
Thermal Conductivity (W/mK)	≥ 3.0	≥ 1.0	≤ 0.25	≤ 0.6
Volume Resistivity (ohm-cm)	≤ 5 x 10 ^{-2*}	≥ 1 x 10 ⁺⁹	≥ 1 x 10 ⁺⁹	≥ 1 x 10 ⁺⁹
Die Shear Adhesion @ 25 °C	≥ 2400	≥ 2400	≥ 2400	≥ 2400





TECHNICAL DATA SHEET Semiconductor Solutions

Typical Properties	591	692	492	892
Elastic Modulus (psi)	≥ 500,000	≥ 500,000	≥ 500,000	≥ 500,000
Glass Transition Temp. (T _g)	≥ 50 °C	≥ 50 °C	≥ 50 °C	≥ 50 °C
Shelf Life @ 25 °C	1 Year	1 Year	1 Year	1 Year

FILM AVAILABILITY

- 1. Sheet material is available in thicknesses of 0.0015", 0.003", and 0.005". Sheet sizes range from 4" x 4" up to a maximum of 10" x 12".
- 2. Preforms: same thicknesses apply. We have a fully equipped stamping facility on site. Provide your dimensions or drawing.
- 3. Rolls / Tape: We have the capability to provide long strips of film adhesive slit to 0.250" or wider for continuous feed bonding machines.

BONDING

Bond film adhesive at 150 to 220 °C. Pressure required is dependent on temperature and dwell time at temperature. Lower temperatures require higher pressures. Higher temperatures require little or no pressure. It is critical that both interfaces to be bonded reach the required temperature. Typical pressures for most applications range from 1 to 10 psi. Time required to form a bond will depend on the application. Bonds can be formed in seconds under optimum conditions. Typical bond times are 10 to 60 seconds. Equipment used for heating can range in sophistication from a hot plate to a box oven or continuous feed belt furnace.





TECHNICAL DATA SHEET Semiconductor Solutions

SAFETY & WARNING

It is recommended that the company/operator read and review the Safety Data Sheets for the appropriate health and safety warnings before use.

Safety Data Sheets are available at techinfo@MacDermidAlpha.com.

STORAGE

Material should be stored at room temperature (25 °C). Do not freeze. It is recommended that film be kept in nitrogen cabinet or desiccator to prevent exposure to moisture. If the material is kept beyond the recommended shelf life, it is not necessarily unusable. But, a quality control should be performed on the properties relevant to the application.

CONTACT INFORMATION

To confirm this document is the most recent version, please contact techinfo@MacDermidAlpha.com

www.macdermidalpha.com

North	Λ	merica

3950 Johns Creek Ct, Suite 300 Suwanee, GA 30024 USA 908.791.2300

Europe

Unit 2, Genesis Business Park Albert Drive Woking, Surrey, GU21 5RW, UK 44.01483.758400

Asia

14 Joo Koon Crescent, Singapore 629014 65.6430.0700

Also read carefully warning and safety information on the Safety Data Sheet. This data sheet contains technical information required for safe and economical operation of this product. READ IT THOROUGHLY PRIOR TO PRODUCT USE. Emergency directory assistance: Chemtrec 1 - 800 - 424 - 9300.

DISCLAIMER: All statements, technical information and recommendations contained herein are based on tests we believe to be reliable, but the accuracy or completeness thereof is not guaranteed. No statement or recommendation shall constitute a representation unless set forth in an agreement signed by officers of seller and manufacturer. NO WARRANTY OF MERCHANTABILITY, WARRANTY OF FITNESS FOR A PARTICULAR PURPOSE OR ANY IMPLIED WARRANTY IS MADE. The following warranty is made in lieu of such warranties and all other warranties, express, implied, or statutory. Products are warranted to be free from defects in material and workmanship at the time sold. The sole obligation of seller and manufacturer under this warranty shall be to replace any noncompliant product at the time sold. Under no circumstances shall manufacturer or seller be liable for any loss, damage or expense, direct, incidental or consequential, arising out of the inability to use the product. Notwithstanding the foregoing, if products are supplied in response to a customer request that specifies operating parameters beyond those stated above, or if products are used under conditions exceeding said parameters, the customer by acceptance or use thereof assumes all risk of product failure and of all direct, indirect, incidental and consequential damages that may result from use of the products under such conditions, and agrees to exonerate, indemnify, defend and hold harmless MacDermid, Incorporated and its affiliates therefrom. No suggestion for product use nor anything contained herein shall be construed as a recommendation to use any product in a manner that infringes any patent or other intellectual property rights, and seller and manufacturer assume no responsibility or liability for any such infringement.

© 2019 MacDermid, Inc. and its group of companies. All rights reserved. "(R)" and "TM" are registered trademarks or trademarks of MacDermid, Inc. and its group of companies in the United States and/or other countries.

